

**$V_F = 1.5\text{ V}$**   
**Through-hole Infrared LED**  
**SID1G307C**

**Description**

The SID1G307C is a through-hole infrared LED.

**Package**

φ5 mm Round  
(with Stopper)

**Features**

- Infrared LED
- Lens Color ----- Clear
- Forward Voltage,  $V_F$ ----- 1.5 V (typ.) ( $I_F = 50\text{ mA}$ )
- Peak Wavelength,  $\lambda_p$ ----- 850 nm
- Viewing Angle,  $2\theta_{1/2}$ ----- 40 deg
- RoHS Compliant
- Pb-free, Soldering
- High Reliability

**Applications**

- Sensor
- Infrared Light Source
- Infrared Communication



(1) Cathode  
(2) Anode

Not to scale

**Absolute Maximum Ratings**Unless specifically noted,  $T_A = 25\text{ }^{\circ}\text{C}$ .

Parameter	Symbol	Conditions	Rating	Unit
Power Dissipation	$P_D$		180	mW
Forward Current	$I_F$		100	mA
Forward Current Reduction	$\Delta I_F$	$T_A \geq 25\text{ }^{\circ}\text{C}$	-1.33	mA/ $^{\circ}\text{C}$
Pulse Forward Current	$I_{FP}$	Frequency = 1 kHz Pulse Width $\leq 10\text{ }\mu\text{s}$	1000	mA
Reverse Voltage	$V_R$		3	V
Operating Temperature	$T_{OP}$		-30 to 85	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$		-30 to 100	$^{\circ}\text{C}$

**Electrical / Optical Characteristics**Unless specifically noted,  $T_A = 25\text{ }^{\circ}\text{C}$ .

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Voltage	$V_F$	$I_F = 50\text{ mA}$	—	1.5	1.8	V
Reverse Current	$I_R$	$V_R = 3\text{ V}$	—	—	10	$\mu\text{A}$
Radiation Intensity	$I_e$	$I_F = 50\text{ mA}$	20	50	—	mW/Sr
Peak Wavelength	$\lambda_P$	$I_F = 50\text{ mA}$	—	850	—	nm
Viewing Angle	$2\theta_{1/2}$	$I_F = 50\text{ mA}$	—	40	—	deg

**Radiation Intensity Bins**

Bin Number	Radiation Intensity Range	Unit
A	20 to 40	mW/Sr
B	26 to 54	mW/Sr
C	35 to 72	mW/Sr
D	47 to 95	mW/Sr
E	63 or more	mW/Sr

Derating Curves

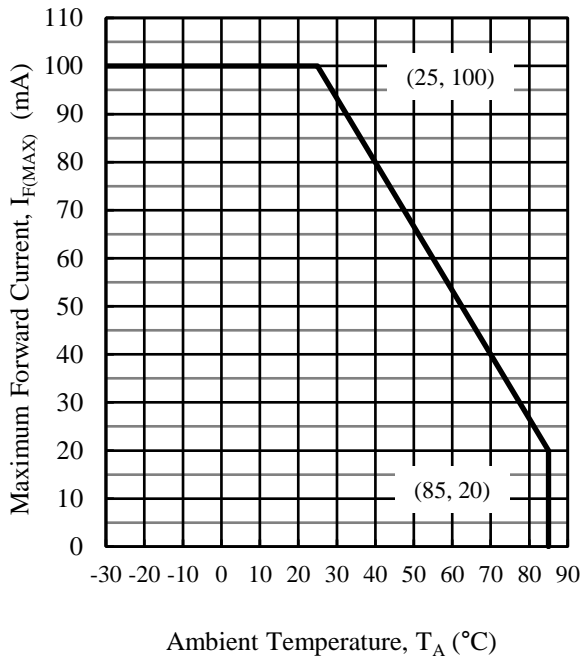


Figure 1.  $I_{F(MAX)}$  vs.  $T_A$

Characteristic Curves

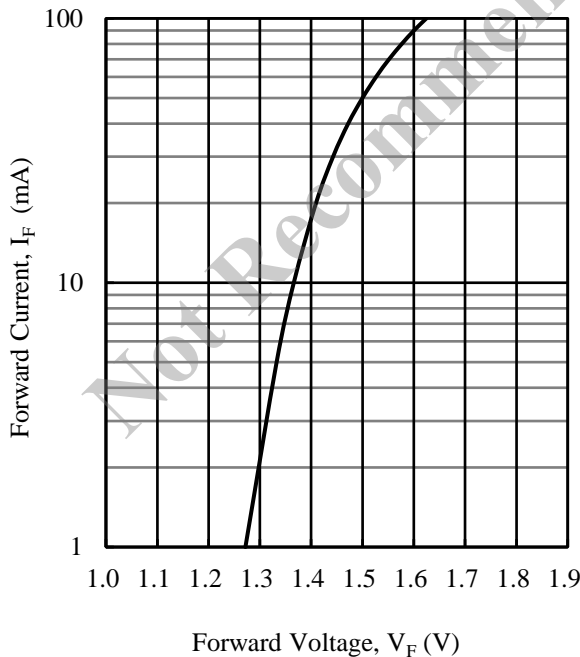


Figure 2.  $I_F$  vs.  $V_F$

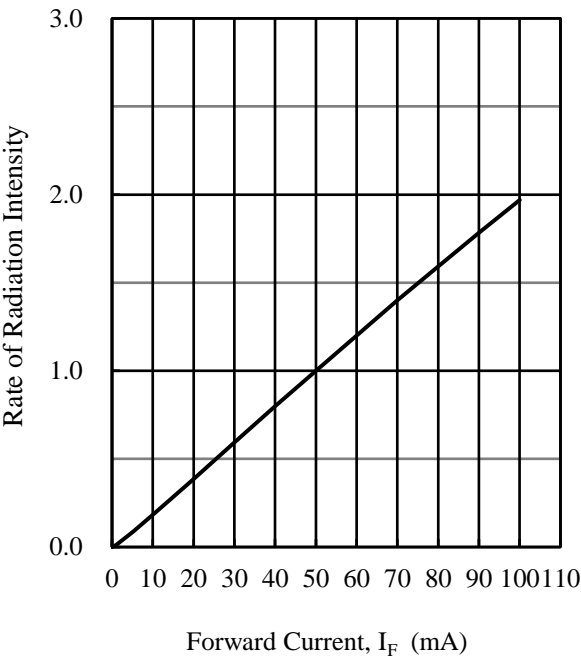


Figure 3. Rate of Radiation Intensity vs.  $I_F$

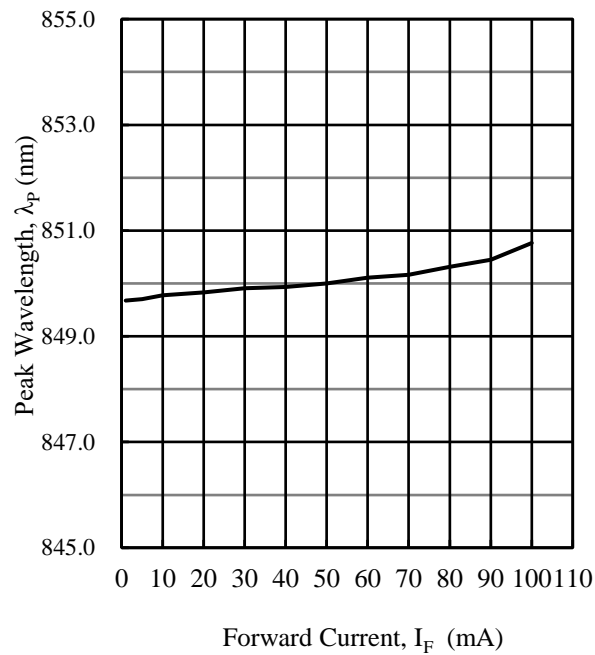


Figure 4.  $\lambda_p$  vs.  $I_F$

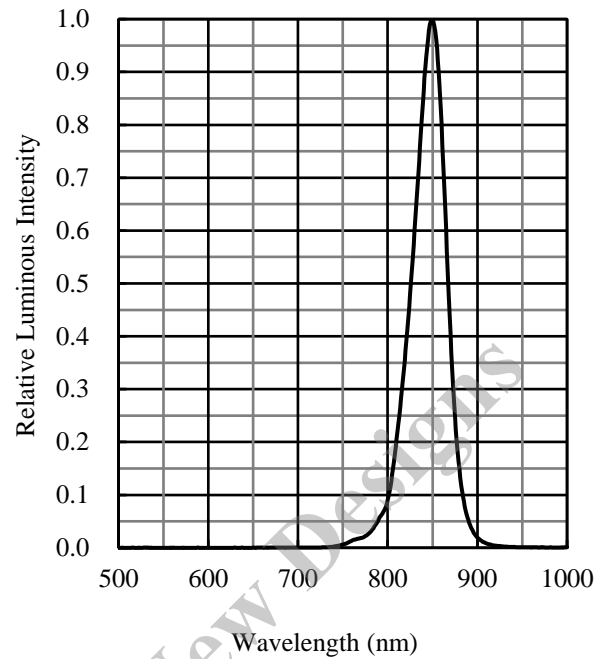


Figure 5. Spectrum ( $I_F = 50$  mA)

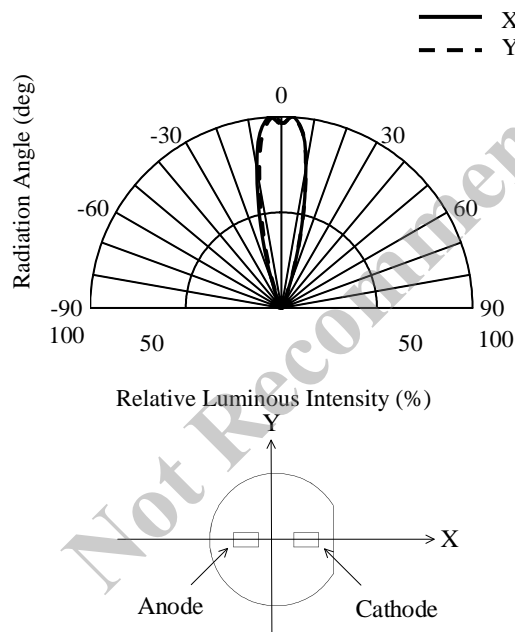
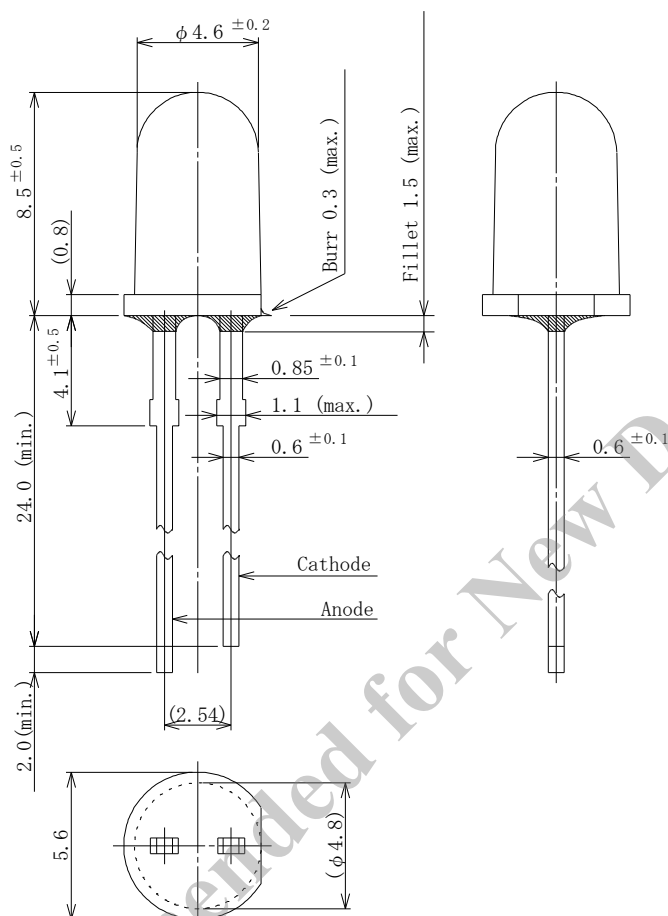


Figure 6. Directivity

## Physical Dimensions

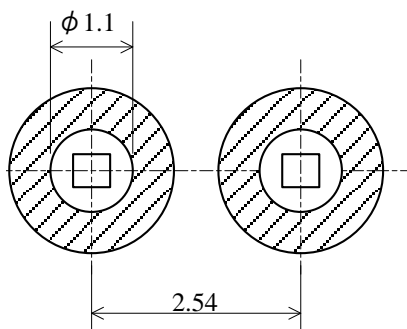
### • Through-hole ( $\phi 5$ mm Round)



#### NOTES:

- Dimensions in millimeters
- Unless specifically noted, tolerance is  $\pm 0.3$ .
- RoHS compliant

### • Land Pattern Example



#### NOTES:

- Dimensions in millimeters
- All the dimensions without tolerance are for reference only.

**Soldering Conditions**

- When soldering the products, it is required to minimize the working time within the following limits:
  - Flow:
    - Preheat: 90 °C / 120 s
    - Solder heating: 250 °C / 3 s
  - Soldering iron: 350 ± 10 °C / 3 s, 1 timeBe sure to ensure a distance of ≥4.0 mm between the encapsulating resin and the solder.
- The following are the considerations in fixing the chip parts to be mounted on the same board as the product. When fixing such chip parts with an adhesive before soldering, extreme care should be taken not to heat the product before the adhesive is firmly cured (e.g., while it is being cured). Firstly, fix the chip parts other than the products with an adhesive. Secondly, heat to cure the adhesive before mounting the product. Finally, mount and solder the product. If there is no choice but to simultaneously heat the product and other chip parts for curing the adhesive, perform the simultaneous heating under the conditions listed below without any external force, stress, or excessive vibration applied to the product. After the adhesive is cured, cool the product to a room temperature and then perform soldering.
  - Solder heating temperature: ≤120 °C
  - Solder heating time: ≤60 s
- A hole pitch to be formed on a board should be identical to the pin pitch of the product.
- When mounting the product on a double-sided board, do not use plated through holes.

**Precautions for Use**

- After soldering the product, care should be taken not to apply mechanical stress or excessive vibration until it cools to room temperature. A glass transition of the product's encapsulating resin will occur at temperatures from about 120 °C to 130 °C. When the resin temperature exceeds these temperatures, the resin softens rapidly. Therefore, applying stress or excessive vibration to the resin or pin at high temperatures may cause a shift in the pin alignment or an internal wire breakage of the LED.
- Do not cool the product rapidly.
- When mounting the product on a board, mounting position and orientation should be taken into account so that any stress due to board warpage is not applied to the product.
- Do not touch the encapsulating resin of the product with sharp objects such as a tweezer or fingernails. Also, do not use the product again after removal.
- Do not touch the product after mounting it on a board.
- The product emits a high-power light. Therefore, care should be taken not to look at the light emission directly for a long time because it may hurt your eyes.
- Use the product at rated current (sorting current) as much as possible. When the product is used at a current lower than the rated current (sorting current), a variation in forward voltage or luminous intensity may increase. Therefore, care should be taken for such variation when you use the product at low current.
- As the product uses gallium arsenide (GaAs), the following must be considered dangerous and be avoided: burning or crushing the product; inhaling or swallowing the liquid or gas generated by any chemical treatment on the product.
- When using the product, care should be taken not to apply a voltage in the opposite direction of the LED.

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DSGN-CEZ-16003